

## N-Channel 30V(D-S) MOSFET

Product summary		
V <sub>DS</sub>	30	V
R <sub>DS(ON)</sub> (at V <sub>GS</sub> =10V) Typ.	8.8	mΩ
R <sub>DS(ON)</sub> (at V <sub>GS</sub> =4.5V) Typ.	13	mΩ
I <sub>D</sub> (T <sub>c</sub> =25°C)	13	A

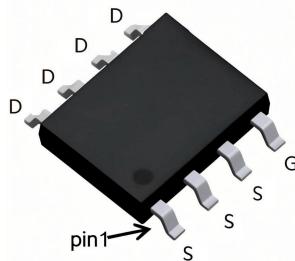
### Features

- Low Gate Charge
- Advanced high cell density Trench technology

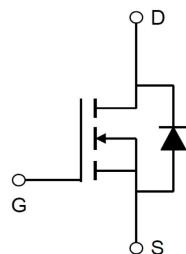
### Applications

- Power management functions

### Pin Configuration



SOP8



### Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECHA13N03S	SOP8	13"	4000pcs

### Absolute Maximum Ratings (at T<sub>A</sub>=25°C Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Continuous Drain Current	T <sub>C</sub> =25°C	A
		T <sub>C</sub> =100°C	A
I <sub>DM</sub>	Pulse Drain Current <sup>A</sup>	52	A
E <sub>AS</sub>	Single Pulse Avalanche Energy <sup>B</sup>	33	mJ
P <sub>D</sub>	Power Dissipation @T <sub>C</sub> =25°C	3.5	W
T <sub>J</sub> , T <sub>STG</sub>	Junction and Storage Temperature Range	-55 to +150	°C

### Thermal Characteristics

Symbol	Parameter	Typical	Units
R <sub>θJA</sub>	Thermal Resistance-Junction to ambient <sup>C</sup>	35.7	°C/W

Electrical Characteristics (at  $T_J = 25^\circ\text{C}$  Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_{\text{D}}=250\mu\text{A}$	30	--	--	V
$\text{I}_{\text{DSS}}$	Zero Gate Voltage Drain Current	$\text{V}_{\text{DS}}=30\text{V}, \text{V}_{\text{GS}}=0\text{V}$	--	--	1	$\mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Body Leakage Current	$\text{V}_{\text{DS}}=0\text{V}, \text{V}_{\text{GS}}=\pm 20\text{V}$	--	--	$\pm 100$	nA
$\text{V}_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_{\text{D}}=250\mu\text{A}$	1.0	1.5	2.5	V
$\text{R}_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance <sup>D</sup>	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_{\text{D}}=13\text{A}$	--	8.8	12	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_{\text{D}}=10\text{A}$	--	13	18	$\text{m}\Omega$
$\text{V}_{\text{SD}}$	Diode Forward Voltage	$\text{I}_{\text{S}}=13\text{A}, \text{V}_{\text{GS}}=0\text{V}$	--	--	1.2	V
$\text{I}_{\text{S}}$	Maximum Continuous Drain to Source Diode Forward Current	$\text{V}_{\text{G}}=\text{V}_{\text{D}}=0\text{V}$	--	--	13	A
Dynamic Parameters <sup>E</sup>						
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=15\text{V}$ $f=1\text{MHz}$	--	1011	--	pF
$\text{C}_{\text{oss}}$	Output Capacitance		--	142	--	pF
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance		--	119	--	pF
$\text{Q}_{\text{g}}$	Total Gate Charge	$\text{V}_{\text{DS}}=15\text{V}, \text{I}_{\text{D}}=6\text{A}$ $\text{V}_{\text{GS}}=10\text{V}$	--	19	--	nC
$\text{Q}_{\text{gs}}$	Gate-Source Charge		--	6.3	--	nC
$\text{Q}_{\text{gd}}$	Gate-Drain Charge		--	4.5	--	nC
$t_{\text{D}(\text{on})}$	Turn-on Delay Time	$\text{V}_{\text{DS}}=15\text{V}$ $\text{I}_{\text{D}}=13\text{A}, \text{R}_{\text{GEN}}=3\Omega,$ $\text{V}_{\text{GS}}=10\text{V}$	--	6	--	ns
$t_{\text{r}}$	Turn-on Rise Time		--	5	--	ns
$t_{\text{D}(\text{off})}$	Turn-off Delay Time		--	25	--	ns
$t_{\text{f}}$	Turn-off Fall Time		--	7	--	ns

A. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

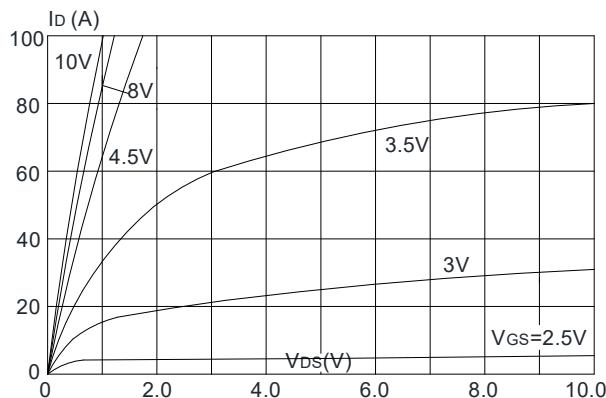
B. The EAS data shows Max. Rating, The test condition is  $\text{V}_{\text{DD}}=15\text{V}, \text{V}_{\text{GS}}=10\text{V}, \text{L}=0.5\text{mH}, \text{I}_{\text{AS}}=6.6\text{A}, \text{R}_g=25\Omega, T_J=25^\circ\text{C}$ .

C. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

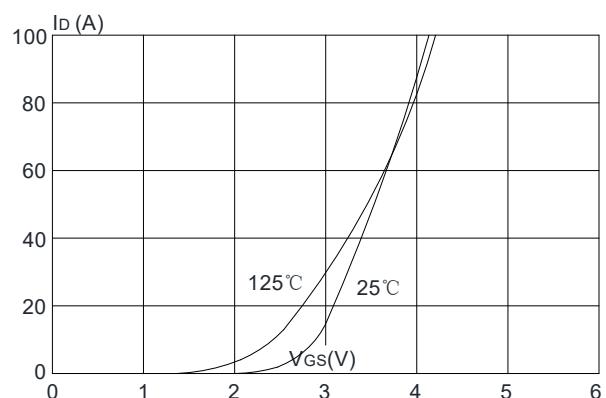
D. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$  , duty cycle $\leq 2\%$ .

E. Guaranteed by design, not subject to production testing.

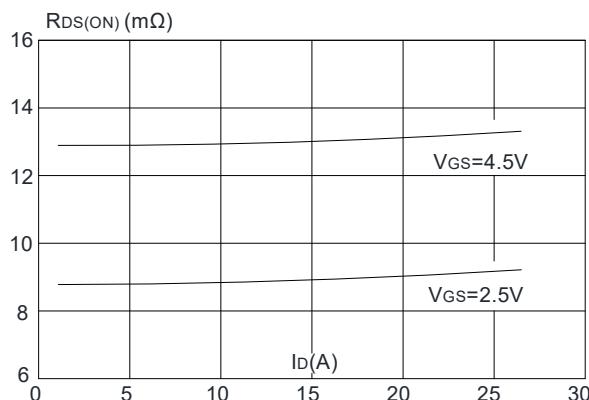
## Typical Characteristics



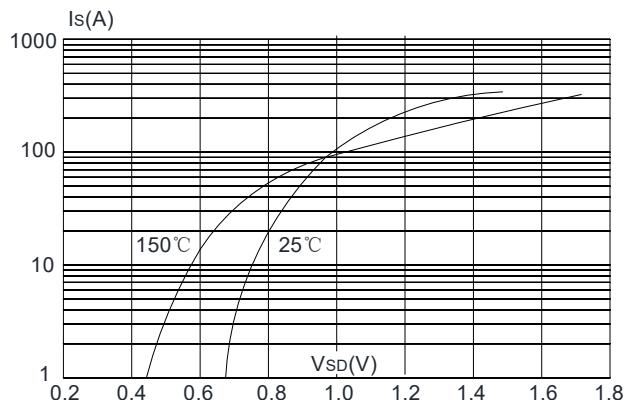
**Figure 1:** Output Characteristics



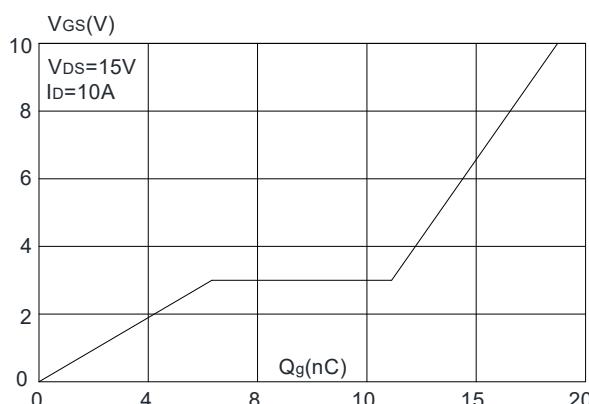
**Figure 2:** Typical Transfer Characteristics



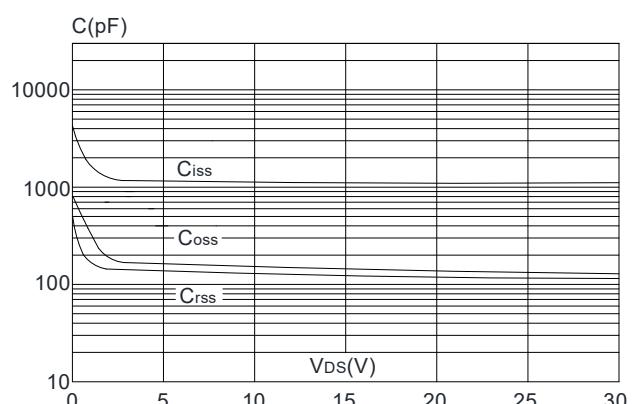
**Figure 3:** On-resistance vs. Drain Current



**Figure 4:** Body Diode Characteristics

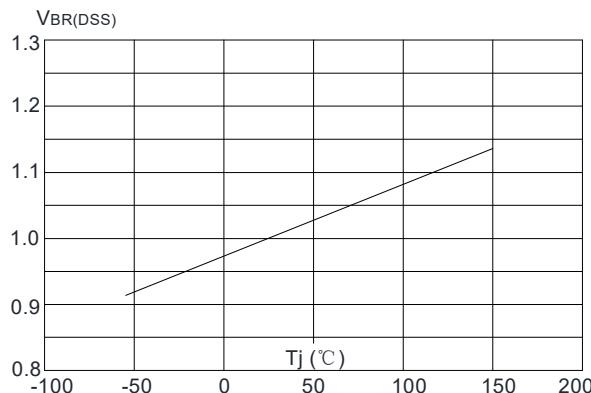


**Figure 5:** Gate Charge Characteristics

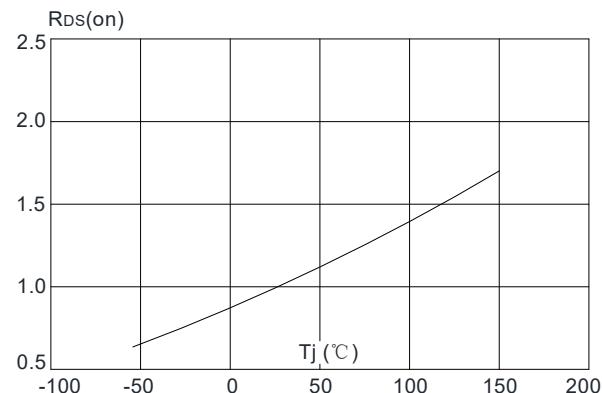


**Figure 6:** Capacitance Characteristics

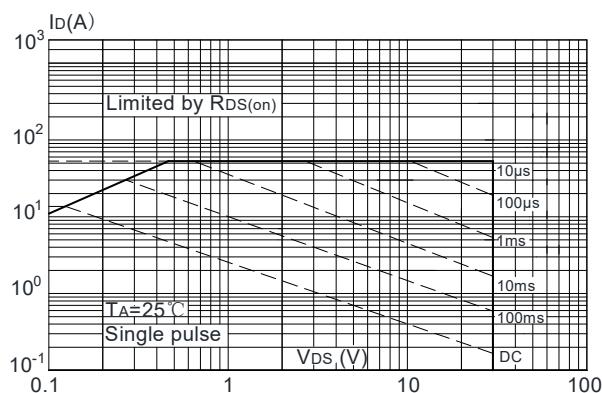
## Typical Characteristics



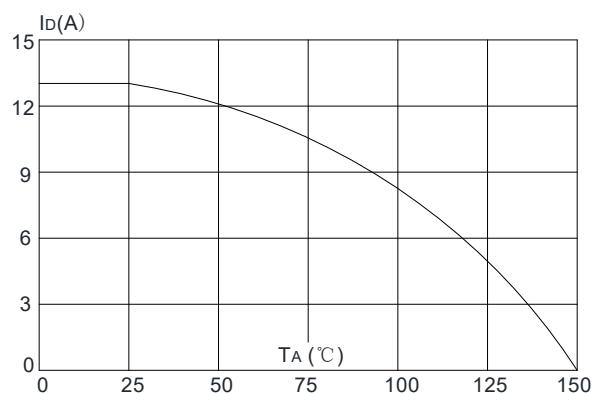
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



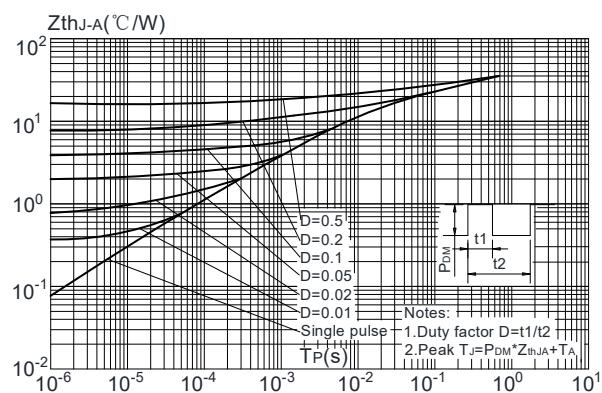
**Figure 8:** Normalized on Resistance vs. Junction Temperature



**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

## Typical Characteristics

### Test Circuit

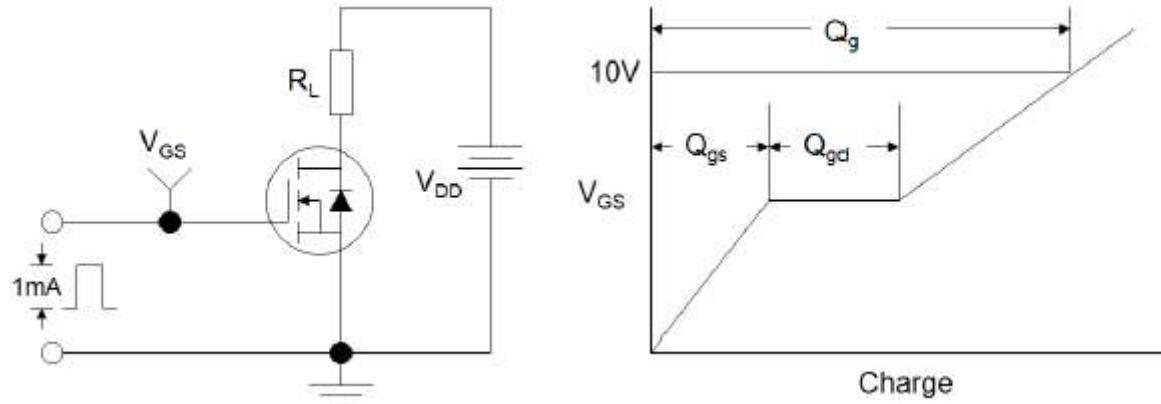


Figure 1: Gate Charge Test Circuit & Waveform

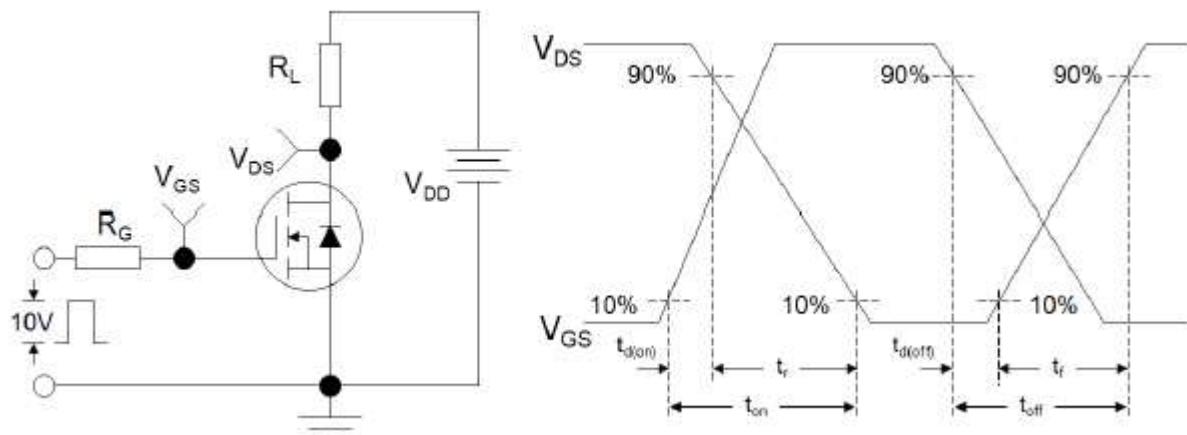


Figure 2: Resistive Switching Test Circuit & Waveforms

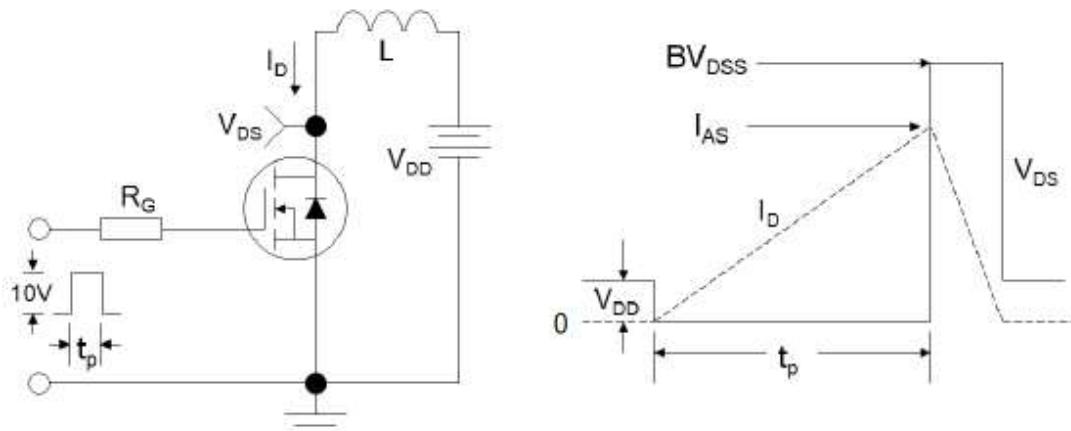
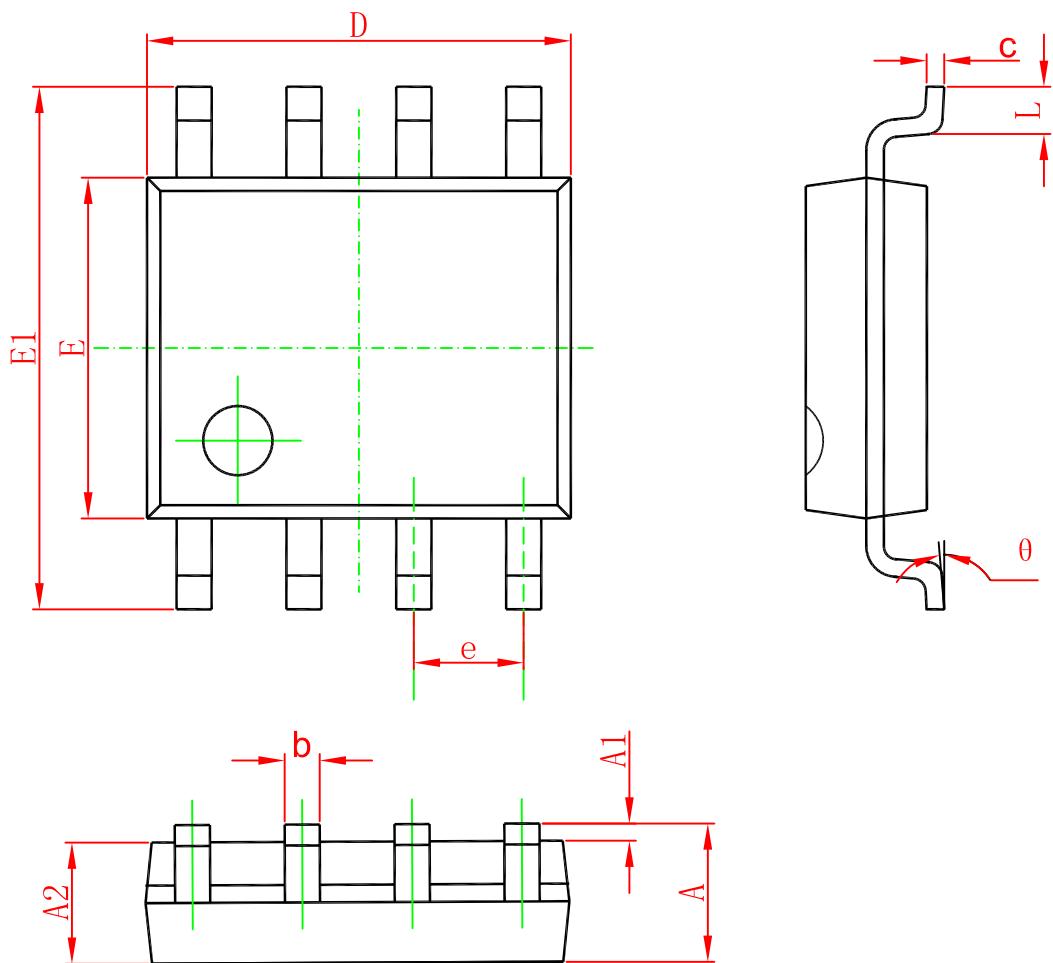


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms

**SOP8 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°